



Canfield Technologies, LLC

TECHNICAL DATA SHEET

FLOSAFE™

DESCRIPTION

97% Tin/3% Copper is alloyed from pure virgin metals and contains tin, and copper. It is economical to use when lead-free solder is required and meets all State and Federal Specifications for potable water applications.

APPLICATIONS

Sealing, joining, coating and filling of all solderable metals. Used in plumbing, heating and industrial applications. The solder to use on brass, bronze, copper, galvanized iron, monel, steel, stainless steel and all other solderable alloys that require maximum reliability of solder joints.

FLUXES

For steel and copper use Canfield's SOLDER-MATE® Liquid Soldering Flux. For copper pipe use COPPER-MATE® Self-Cleaning Soldering Paste Flux or AQUA-BRITE Water Soluble Flux. On stainless steel use SIL-CAN® Liquid Soldering Flux.

TEMPERATURE RANGE:	440 - 590° F (room temperature)
SHEAR STRENGTH:	6,500 PSI (room temperature)
TENSILE STRENGTH:	5,500 PSI (room temperature)
DENSITY:	.264 pounds per cubic inch
ELECTRICAL CONDUCTIVITY:	8.5 Sm/mm ²

PACKAGING AND STORAGE INFORMATION

Available in bar, solid wire, cored wire. Fine wire sizes are also available. Please call for your specific needs.

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